



# **ELECTRONIC TECHNOLOGY CO., LTD.**

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Rev.	1.0		
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# CRYSTAL UNIT SPECIFICATIONS

客户批准 Customer Approval

(请批准后回签一份 Please Return A Copy With Appoval)

Customer	
Customer P/N	
Product	TUNING FORK CRYSTAL
Spec	DTLF308/32.768K/12.5PF/+-20PPM
A-Crystal P/N	AD33276812503T4

Drawn	Checked	Approved
caogaobang	tanglong	huangweilong

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No: SC-GF-15-12-01





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# 1. ELECTRICAL SPECIFICATIONS

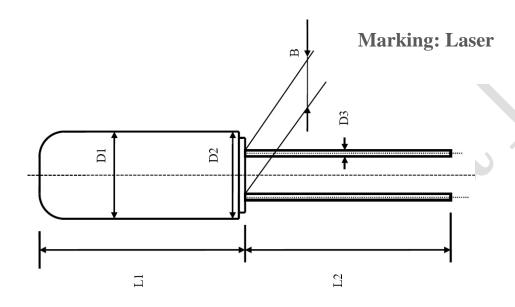
1.1 Hold Type: DTLF308

Parameter	Symb	Value	Condition
Frequency Range	F <sub>0</sub>	32.768Khz	
Frequency Tolerance	∆f/fo	±20PPM	REF TO 25℃
Temperature Coefficient	K	-0.034±0.006 ppm/(°C) <sup>2</sup>	
Turnover Temperature	T <sub>TO</sub>	<b>25</b> ±5℃	
Operating Temperature Range	T <sub>OP</sub>	-20℃ to 70℃	
Storage Temperature Range	T <sub>ST</sub>	-40°C to 85°C	
Quality Factor	Q	60,000TYP	
Series Resistance	R <sub>1</sub>	<b>30 K</b> Ω	KΩMax REF TO 25°C
Shunt Capacitance	Co	1.8 PF TYP	0.9~2.0PF
Motional Capacitance	C <sub>1</sub>	2.1 Ff TYP	4 Ff Max
Load Capacitance	$C_{\mathrm{L}}$	12.5 PF	
Insulator Resistance	IR	500 M Ω	DC100V±15V
Drive Level	DL	1 ц W	Max
Capacitance ratio	R	450TYP	
Aging	△/f	±5 PPM	at 25°C ±3°C



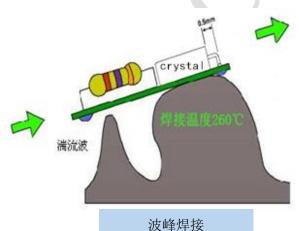
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### 1.2 Dimension (Unit: mm)

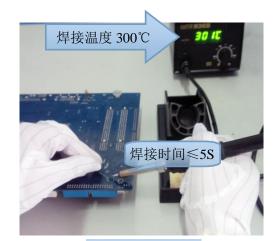


型号/尺寸	L1	L2	D1	D2	D3	В
3*8	8.3Max	9.0Min	$2.95 \pm 0.1$	$3.0\pm0.1$	$0.3 \pm 0.05$	$0.8 \pm 0.05$

# 1.3The soldering requirements



放峰焊接 Wave Solder Profile



手工焊接 Manual Welding





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#### 2. TEST STANDARD

#### 2.1 GENERAL ELECTRICAL CHARACTERISTICS AND VISUALTESTING

- 2.1.1 LOT CLASSIFICATION: If the quantity is 1000 PCS or more, 1000 PCS is one lot
- 2.1.2 SAMPLING TEST METHOD: MIL-STD-105E G-II
- 2.1.3 TEST LEVEL
  - A) HIGH LEVEL DEFECT: AQL 0.065% [200 pcs]
  - B) MEDIUM LEVEL DEFECT : AQL 0.25% [50 pcs]
  - C) LOW LEVEL DEFECT : AQL 0.4% [32 pcs]
- 2.1.4 DEFECT CLASSIFICATION
  - A) HIGH LEVEL
    - **@NO FREQUENCY**
    - @MIXING
    - **@LEAK DEFECT**
  - B) MEDIUM LEVEL ELECTRICAL CHARACTERISTIC DEFECT
    - **@FREQUENCY**
    - @OSCILLATION
    - **@ELECTRICAL CURRENT**
    - **@OTHER ELECTRICAL CHARACTERISTICS DEFECT**
  - C) VISUAL
    - @MARKING
    - @WELDING
    - @LEADS
    - **@OTHER VISUAL DEFECT**

TESTING METHOD AND ITS STANDARD CAN BE MODIFIED DEPENDING ON THE CUSTOMER'S REQUEST

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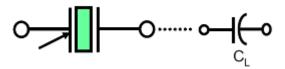
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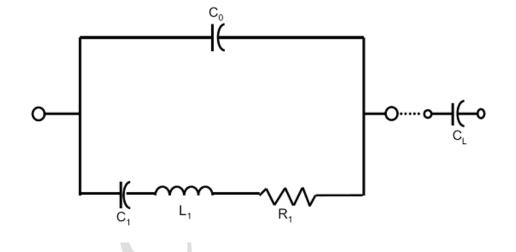


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# 2.2 Equivalent Circuits



Symbol for crystal unit



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# 3.RELIABILITY(MECHANICAL AND ENVIRONMENTAL ENDURANCE)

NO.	TEST	TEST METHOD AND CONDITION	REQUIREMENTS
1	VIBRATION	(1)VIBRATION FREQUENCY: 10 TO 55HZ (2)VIBRATION AMPLITUDE: 1.5MM (3)CYCLE TIME: 1~2MIN(10-55-10HZ) (4)DIRECTION: X.Y.Z (5)DURATION: 2H/EACH DIRECTION (6)G-FORCE: ≥5G	FREQUENCY CHANGE: ±10PPM MAX. RESISTANCE CHANGE: ≤ KΩ.
2	SHOCK	3 TIMES FREE DROP FROM 75CM HEIGHT TO HARD WOODEN BOARD OF THICKNESS MORE THAN 30MM.	FREQUENCY CHANGE: ±10PPM MAX. RESISTANCE CHANGE: ≤ 5 KΩ.
3	LEAKAGE	<ol> <li>PUT CRYSTAL UNITS INTO A HERMETIC</li> <li>CONTAINER AND HELIUM FOR 0.5-0.6.</li> <li>MPA, ND KE P IT FOR 1H; HECK THE LEAKAGE BY A HELIUM LEAK DETECTOR.</li> </ol>	LEAKAGE:1X10 <sup>-</sup> 8MBAR.L /S MAX.
4	SOLDERABILITY	(4) DIP THE LEADS INTO FLUX(ROJIN METHANOL) FOR 3~5S. (5) DIP THE LEADS INTO 245 ±5 °C 99% SN DIPPING SOLUTION FOR 5S.	
5	SOLDERING HEAT RESI ISTANCE TEST	(1) PERFORM ELECTRICAL CHARACTERISTICS TEST BEFORE STARTING THIS PROCEDURE. (2) DIP THE LEADS INTO FLUX(ROJIN METHANOL) 5±0.5S. (3) DIP THE LEADS INTO 260±5°C 99% SN DIPPING SOLUTION FOR 5S. (4) TAKE THE UNIT OUT ,STORE AT ROOM TEMPERATURE FOR 30S THEN MEASURE THE ELCTRICAL CHARACTERISTICS.	SHOULD PASS SEALING AND VISUAL TEST. FREQUENCY CHANGE: ±10PPM MAX.
6	I LEAK IEST	USE HELIUM LEAK DETECTOR. BOMBING PRESSURE:5KG/CM <sup>2</sup> BOMBING TIME: 2 HOURS LEAK SHOULD BE LESS THAN 1E-8 ATM.CC/SEC.	GAS OR AIR SHOULD NOT BE DETECTED.
7	HIGH TEMPERATURE ENDURANCE	SOMEWHERE FOR 500 HOURS AT TEMPERATURE OF	FREQUENCY CHANGE: ±10PPM MAX. RESISTANCE CHANGE: ≦5 KΩ.





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NO.	TEST ITEMS	TEST METHOD AND CONDITION	REQUIREMENTS
8	LOW TEMPERATURE ENDU ANCE	THE CRYSTAL UNITS SHALL BE PUT IN SOMEWHERE FOR 500 HOURS AT TEMPERATURE OF -40°C, THEN KEEP IT FOR 1 TO 2 HOURS UNDER ROOM.	FREQUENCY CHANGE: $\pm 10$ PPM MAX. RESISTANCE CHANGE: $\leq 5$ K $\Omega$ .
9	HUMIDITY ENDURANCE	SOMEWHERE AT 40°C ±5°C IN RELATIVE HUMIDITY OF 90%~95% FOR 72 HOURS, THEN KEEP IT FOR ONE OR TWO HOURS UNDER ROOM TEMPERATURE	FREQUENCY CHANGE: ±10PPM MAX. RESISTANCE CHANGE: ≤ 5 KΩ.
10	TEMPERATURE CYCLE	TEMPERATURE SHIFT FROM LOW(-40°C) TO HIGH(100°C, KEEP 30 MINUTES), SATISFY HIGH(100°C) TO LOW(-40°C, KEEP 30 MINUTES), THEN GO UP TO ROOM TEMPERATURE FOR 10 CYCLES.	FREQUENCY CHANGE: ±10PPM MAX. RESISTANCE CHANGE: ≤ 5 KΩ.
11	LEAD TENSILTY	(1) FIX THE UNIT. (2) APPLY 2LB OF WEIGHT AXIS TO THE LESDS. (3) TIME:5S	
12	LEAD BENDING	(1) ATTACH 1LB OF WEIGHT TO EACH OF THE LEADS. (2) BENDING ANGLE:90°C (FROM THE NOMAL POSITION TO 45°C OPPOSTTE DIRECTION) (3) BENDING TIME:3S(EACH DIRECTION) (4) NUMBER OF BENDING:2TIMES	SHOULD PASS SEALING AND VISUAL TEST.
13	MARKING ERASE	SUBMERGE THE UNIT INTO IPA[ISOPROPYL ALCOHOL] SOLUTION FOR 10MINUTES AND BRUSH THE MARKING 10 TIMES WITH A TOOTH BRUSH.	MARKING SHOULD NOT BE ERASED.





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#### 4. PACKING

#### 4.1 Section of package

Package is made of corrugated paper with thickness of 0.8cm.Package has 10 inner boxes, each box has 10 bag

4.1.1 Quantity of package

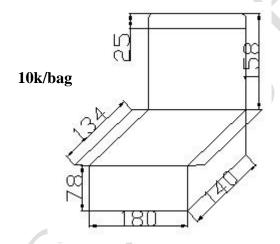
Per plastic bag 1000 pieces of Crystal Resonators

Per inner box 10 bag (1k/bag)

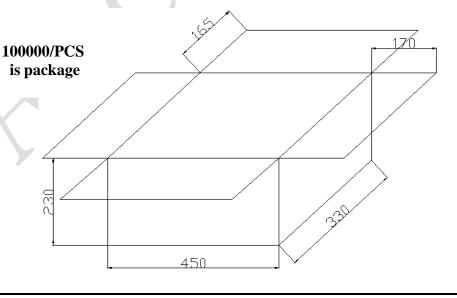
Per package 10 inner boxes

(100000 pieces of Crystal Resonators)

#### 4.1.2 Inner Box Dimensions (Unit: mm)



#### 4.1.3 Dimensions and Mark (Unit: mm)







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#### 5. CAUTION

\* IN ORDER TO MAINTAIN QUALITY. WITHOUT CHANGE IN CHARACTERISTICS OF THECRYSTAL UNITS.PLEASE FOLLOW BELOW RECOMMENDATION

#### 5.1 SHOCK

- 5.1.1 ALL CRYSTAL UNITS HAVE A THIN CRYSTAL BLANKS WITHIN IF IT IS DROPPED ABOVE THE ECOMMENDED DROPPING HEIGHT(500mm) THE SPECIFIC HARACTERISTICS AND APPEARANCE CAN BE CHANGED PLEASE PAY SPECIAL ATTENTION TO EXTERNAL SHOCK
  - 5.2. ENVIRONMENTAL
- 5.2.1 CRYSTAL UNITS' FREQUENCY CAN BE CHANGED DUE TO SURROUNOING TEMPERATURE IF IT IS STORED NEXT TO A HIGH TEMPERATURE HETER (ABOVE+85'C) OR BELOW 40'C.AND A STRONG LIGHT SOURCE FOR LONG PERIOD OF TIME. THE ELECTRICAL CHARACTERISTICS CAN BE CHANGED IT IS SUGGESTED THAT THESE ENVIROMENTS BE AVOIDED
- 5.2.2 IF THE UNIT IS PLACED IN A HUMID ENVIRONMENT. LEAD TERMINAL CAN BE DAMAGED: THEREFORE.DO NOT STORE THE CRYSTAL UNITS IN A HUMID **ENVIRONMENT**
- 5.2.3 CRYSTALUNIT HAS VIBRATING CHARACTERISTICS IF IT IS PLACED WHERE VIBRATION EXISTS THE OPERATING CHARACTERISTICS CAN BE ALTERED: THEREFORE THIS ENVIRONMENT SHOULD BE AVOIDED
  - 5.3 LEADS
- 5.3.1 IF THE LEADS ARE BENT 90 FROM ITS AXIS FOR MORE THAN 2 TIMES THE TERMINAL COULD BE DISCONNECTED; THEREFORE DO NOT BENT THE LEADS
- 5.3.2 AFTER SOLDERING CRYSTAL UNITS INTO A PCB IMPACTING THE UNIT FROM THETOP, BOTTOM LEFT OR RIGHT SIDE OF THE UNIT CAN SHATTER THE GLASS PORTION OF THE BASE AENDERING THE UNIT USELESS
  - 5.4 ASSEMBLY METHOD
- 5.4.1 CORRECT ULTRASONIC FREQUENCY FOR CLEANING SHOULD BE LESS THAN 20KHZ
  - 5.4.2 SOLDERING SHOULD BE BONE USING IEC 61760-1 OR PB-Free Products
  - 5.5 STORAGE
- 5.5.1 IF THE CRYSTAL UNITS ARE STORED IN HUMID OR SALTY ENVIRONMENT APPEARANCE CAN BE CHANGED AND SOLDERABILITY CAN DETERIORATE; THEREFORE AOID STORING IN SUCH ENVIRONMENT DO NOT STORE THE CRYSTAL **UNIT MORE THAN 3 MONTHS**





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#### 6. Pb-Free PRODUCTS

A-crystal Pb-free program.

The A-crystal Pb-free program is implemented in accordance with European Union (EU) Legislation titled "Restriction of the use of certain Hazardous Substances (RoHS)" including banning the use of Pb in electronic assemblies after July 1, 2006.

#### A-crystal Definitions

Pb-Free Classification: Component and Assembly Pb content shall be less than 0.1% by weight of the device (in accordance to IPC/EIA J-STD-006) and shall not be intentionally introduced.

Components: A-crystal's definition of components apply to quartz crystal devices Assemblies: A-crystal's definition of assemblies apply to oscillator devices (XO, VCXO and TCXO's)

#### Recommended Solder Composition

A- crystal's is following industry trend of using alloy range Sn-Ag(3.4-4.1)-Cu(0.45-0.9) for reflow and wave soldering.

#### Pb-free Part Number Identification:

When applicable, the A-crystal specification sheet shall indicate if the device is classified as Pb-free.

Marking and Labeling: A-crystal has a Pb-free labeling method for the packaging of all Pb-free products. The lowest level shipping container shall identify the products as Pb-free.

#### **OTHERS**

If you have some doubt or unknowing about this specification, Please contact us for Settlement or development.